



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-07-28
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HNZJ*F83B81B	A	ZA41	2014-07-28
Amount	UoM	Unit type	ST ECOPACK Grade	
98.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	4.50X2.16X3.68	1	J bend	
Comment	SMB CLIP (SOD 6 NEW); MD valid for CP:STTH2R06U.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-16th December 2013			
Query			Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH			true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application
			ppm in product

Material Composition Declaration						Mfr Item Name	HNZJ*F838818					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon die	Other inorganic materials	1.233	mg	supplier	Die	Silicon (Si)	7440-21-3		1.195	mg	969181	12194
Silicon die				supplier	metallization	Aluminium (Al)	7429-90-5		0.007	mg	5677	71
Silicon die				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	1622	20
Silicon die				supplier	metallization	Nickel (Ni)	7440-02-0		0.005	mg	4055	51
Silicon die				supplier	metallization	Gold (Au)	7440-57-5		0.003	mg	2433	31
Silicon die				supplier	backside metallization	Titanium (Ti)	7440-32-6		0.001	mg	811	10
Silicon die				supplier	backside metallization	Gold (Au)	7440-57-5		0.002	mg	1622	20
Silicon die				supplier	backside metallization	Nickel (Ni)	7440-02-0		0.008	mg	6488	82
Silicon die				supplier	passivation	Gamma-butyrolactone	96-48-0		0.007	mg	5677	71
Silicon die				supplier	passivation	Polyhydroxyamide	55295-98-2		0.003	mg	2433	31
Leadframe + Clip	Copper and its alloy	40.683	mg	Supplier	Alloy	Cu	7440-50-8		40.663	mg	999508	414929
Leadframe + Clip				Supplier	Alloy	Zn	7440-66-6		0.002	mg	49	20
Leadframe + Clip				Supplier	Alloy	Fe	7439-89-6		0.004	mg	98	41
Leadframe + Clip				Supplier	Alloy	Iron Phosphide(FeP)	26508-33-8		0.014	mg	344	143
Die attach	Other organic material	2.311	mg	Supplier	soft solder	Ag	7440-22-4		0.058	mg	25097	592
Die attach				Supplier	soft solder	Sn	7440-31-5		0.115	mg	49762	1173
Die attach				JIG R	soft solder	Lead	7439-92-1	7a-Lead in high me	2.138	mg	925141	21816
Encapsulation	Other organic material	52.838	mg	Supplier	Molding Compound	silica fused	7631-86-9		39.1	mg	739998	398980
Encapsulation				Supplier	Molding Compound	silica quartz	14808-60-7		10.567	mg	199989	107827
Encapsulation				Supplier	Molding Compound	phenolic resin	9003-35-4		2.642	mg	50002	26959
Encapsulation				Supplier	Molding Compound	carbon black	1333-86-4		0.529	mg	10012	5398
Finishing	Other inorganic material	0.935	mg	Supplier	connection coating	Sn	7440-31-5		0.935	mg	1000000	9541